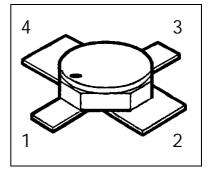


### HiRel NPN Silicon RF Transistor

- HiRel Discrete and Microwave Semiconductor
- For low noise, high-gain broadband amplifiers at collector currents from 0,5 mA to 12 mA.
- Hermetically sealed microwave package
- f<sub>T</sub>= 8 GHz
   F = 2.2 dB at 2 GHz
- Space Qualified

ESA/SCC Detail Spec. No.: 5611/006

Type Variant No. 03



**ESD**: Electrostatic discharge sensitive device, observe handling precautions!

Туре	Marking	Ordering Code	Pin Configuration		Package		
BFY181 (ql)	-	see below	С	Е	В	Е	Micro-X1

(ql) Quality Level: P: Professional Quality, Ordering Code: Q62702F1607
H: High Rel Quality, Ordering Code: on request
S: Space Quality, Ordering Code: on request
ES: ESA Space Quality, Ordering Code: Q62702F1715

(see order instructions for ordering example)



## **Maximum Ratings**

Parameter	Symbol	Values	Unit	
Collector-emitter voltage	V <sub>CEO</sub>	12	V	
Collector-emitter voltage, V <sub>BE</sub> =0	V <sub>CES</sub>	20	V	
Collector-base voltage	V <sub>CBO</sub>	20	V	
Emitter-base voltage	V <sub>EBO</sub>	2	V	
Collector current	I <sub>C</sub>	20	mA	
Base current	I <sub>B</sub>	2 <sup>1)</sup>	mA	
Total power dissipation, $T_S \le 137^{\circ}C^{-2), 3)}$	P <sub>tot</sub>	175	mW	
Junction temperature	Tj	200	°C	
Operating temperature range	T <sub>op</sub>	-65+200	°C	
Storage temperature range	$T_{stg}$	-65+200	°C	
Thermal Resistance				
Junction-soldering point 3)	R <sub>th JS</sub>	< 360	K/W	

### Notes.:

### **Electrical Characteristics**

at  $T_A=25$ °C; unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Collector-base cutoff current	I <sub>CBO</sub>	-	-	100	μΑ
$V_{CB} = 20 \text{ V}, I_E = 0$					
Collector-emitter cutoff current	I <sub>CEX</sub>	-	-	100	μΑ
$V_{CE} = 12 \text{ V}, I_B = 0.1 \mu A^{-1.3}$					
Collector-base cutoff current	I <sub>CBO</sub>	-	-	50	nA
$V_{CB} = 10 \text{ V}, I_E = 0$					
Emitter base cuttoff current	I <sub>EBO</sub>	-	-	25	μΑ
$V_{EB} = 2 V, I_{C} = 0$					
Emitter base cuttoff current	I <sub>EBO</sub>	-	-	0.5	μΑ
$V_{EB} = 1 \text{ V}, I_{C} = 0$					

# Notes:

1.) This Test assures V(BR)CE0 > 12V

<sup>1)</sup> The maximum permissible base current for V<sub>FBE</sub> measurements is 15mA (spotmeasurement duration < 1s)

<sup>2)</sup> At  $T_S = +137$  °C. For  $T_S > +137$  °C derating is required. 3)  $T_S$  is measured on the collector lead at the soldering point to the pcb.



# **Electrical Characteristics** (continued)

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics	·				•
Base-Emitter forward voltage	$V_{FBE}$	-	-	1	V
$I_E = 15 \text{ mA}, I_C = 0$					
DC current gain	h <sub>FE</sub>	55	100	175	-
$I_C = 5$ mA, $V_{CE} = 6$ V					
AC Characteristics					
Transition frequency	f <sub>T</sub>				GHz
$I_{C}$ = 10 mA, $V_{CE}$ = 5 V, f = 500 MHz		6.5	7.5	-	
$I_{C}$ = 10 mA, $V_{CE}$ = 8 V, f = 500 MHz		-	8	-	
Collector-base capacitance	ССВ	-	0.21	0.29	pF
$V_{CB} = 10 \text{ V}, V_{BE} = \text{vbe} = 0, f = 1 \text{ MHz}$					
Collector-emitter capacitance	C <sub>CE</sub>	-	0.34	-	pF
$V_{CE}$ = 10 V, $V_{BE}$ = vbe = 0, f = 1 MHz					
Emitter-base capacitance	C <sub>EB</sub>	-	0.45	0.6	pF
$V_{EB} = 0.5V$ , $V_{CB} = vcb = 0$ , $f = 1 MHz$					
Noise Figure	F	-	2.2	2.9	dB
$I_C = 4$ mA, $V_{CE} = 5$ V, $f = 2$ GHz,					
$Z_S = Z_{Sopt}$					
Power gain	Gma <sup>1.)</sup>	13.5	14.5	-	dB
$I_{C} = 10 \text{ mA}, V_{CE} = 5V, f = 2 \text{ GHz}$					
$Z_S = Z_{Sopt}$ , $Z_L = Z_{Lopt}$					
Transducer gain	$\left S_{21\mathrm{e}}\right ^2$	10	11	-	dB
$I_{C} = 10 \text{ mA}, V_{CE} = 5 \text{ V}, f = 2 \text{ GHz}$					
$Z_S = Z_L = 50 \Omega$					

# Notes.:

1) 
$$G_{ma} = \left| \frac{S21}{S12} \right| (k - \sqrt{k^2 - 1}), \quad G_{ms} = \left| \frac{S21}{S12} \right|$$



#### **Order Instructions:**

Full type variant including quality level must be specified by the orderer. For *HiRel* Discrete and Microwave Semiconductors the ordering code specifies device family and quality level.

Ordering Form:

Ordering Code: Q.....

BFY181 (ql)

(ql): Quality Level

Ordering Example:

Ordering Code: Q62702F1715

BFY181 ES

For BFY181 in ESA Space Quality Level

#### **Further Informations:**

See our WWW-Pages:

- Discrete and RF-Semiconductors (Small Signal Semiconductors) www.infineon.com/products/discrete/hirel.htm

 HiRel Discrete and Microwave Semiconductors www.infineon.com/products/discrete/hirel.htm

Please contact also our marketing division:

Tel.: ++89 234 24480

Fax.: ++89 234 28438 e-mail: martin.wimmers@infineon.com

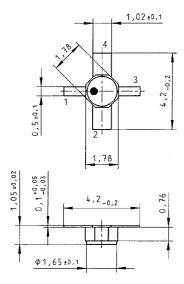
Address: Infineon Technologies Semiconductors,

High Frequency Products Marketing,

P.O.Box 801709, D-81617 Munich



# Micro-X1 Package



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